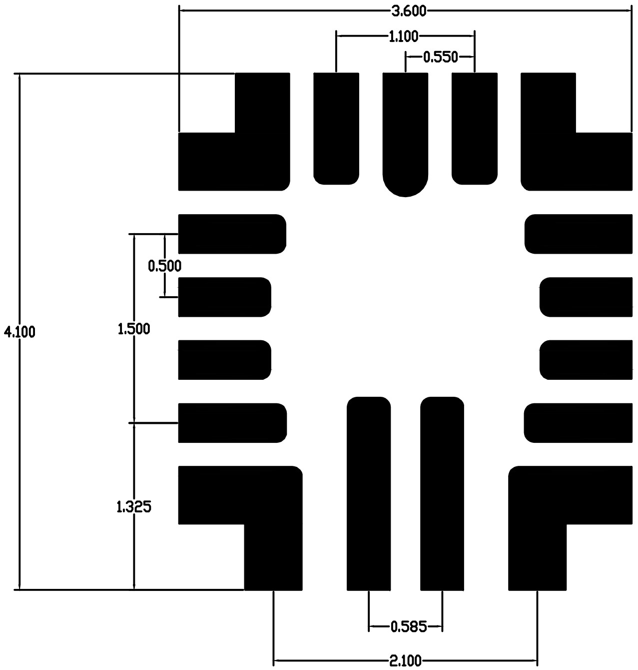
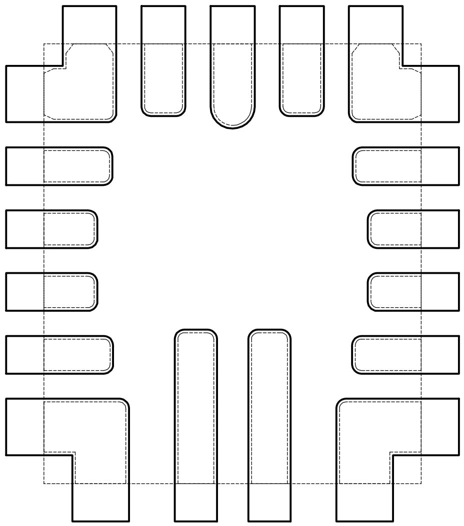
DOCUMENT TYPE:	**PLP**
DOCUMENT ID #:	**90-100189**
REVISION:	**A-000**
DOCUMENT TITLE:	**PACKAGE LAND PATTERN, [F173C3FY+1] FC2QF**
EFFECTIVE DATE:	**09/15/2020**
EXPIRATION DATE:	
CHANGE NUMBER:	**1099994**
ORIGINATOR:	**Bernard Go**

REASON FOR CHANGE:
INITIAL RELEASE

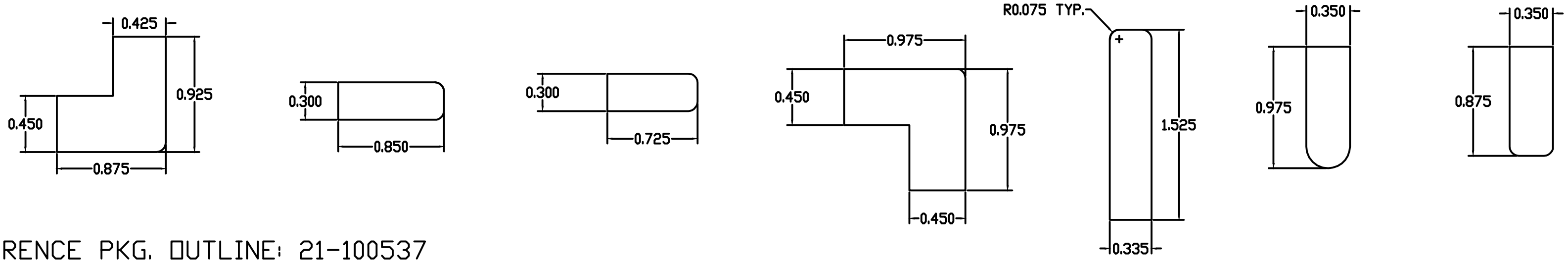
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAILS



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100537
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at http://www.maxim-ic.com/support for further questions.

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TITLE: PACKAGE LAND PATTERN, [F173C3FY+1] FC2QFN			
APPROVAL YUANYUAN WEN	DOCUMENT CONTROL NO. 90-100189	REV. A	1/1

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1099994. Initial release.	09/15/20	BG